Lattice Semiconductor Corporation - LFSC3GA115E-5FCN1152C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga115e-5fcn1152c

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DLLs and dynamic glitch free clock MUXs which are required in today's high end system designs. High-speed, high-bandwidth I/O make this family ideal for high-throughput systems.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeSC family of FPGA devices. Synthesis library support for LatticeSC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeSC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeSC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Innovative high-performance FPGA architecture, high-speed SERDES with PCS support, sysMEM embedded memory and high performance I/O are combined in the LatticeSC to provide excellent performance for today's leading edge systems designs. Table 1-3 details the performance of several common functions implemented within the LatticeSC.

Table1-3. Speed Performance for Typical Functions[1]

Functions	Performance (MHz)[2]
32-bit Address Decoder	539
64-bit Address Decoder	517
32:1 Multiplexer	779
64-bit Adder (ripple)	353
32x8 Distributed Single Port (SP) RAM	768
64-bit Counter (up or down counter, non-loadable)	369
True Dual-Port 1024x18 bits	372
FIFO Port A: x36 bits, B: x9 bits	375

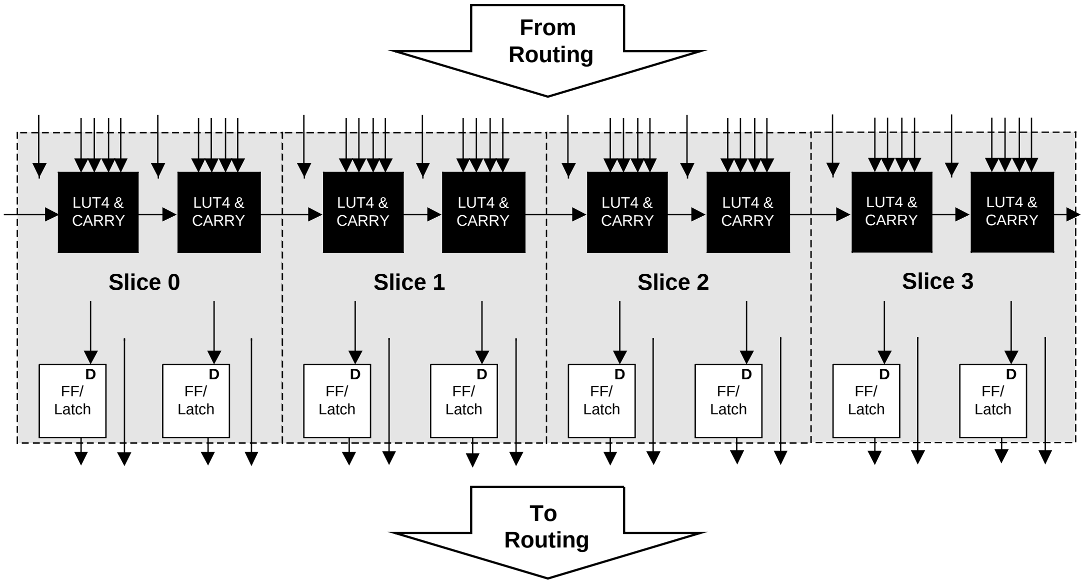
1. For additional information, see Typical Building BLock Function Performance table in this data sheet.
2. Advance information (-7 speed grade).

PFU Blocks

The core of the LatticeSC devices consists of PFU blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram



Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to implement 5, 6, 7 and 8 Input LUTs (LUT5, LUT6, LUT7 and LUT8). There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

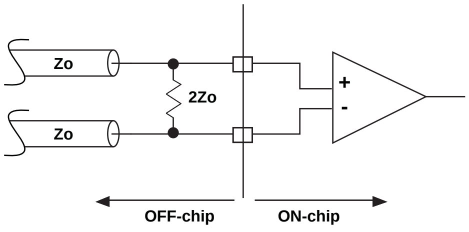
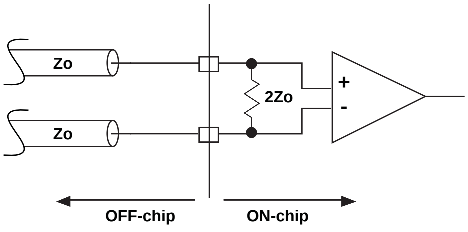
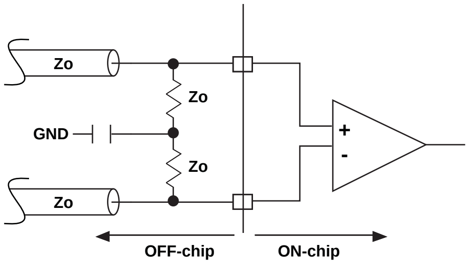
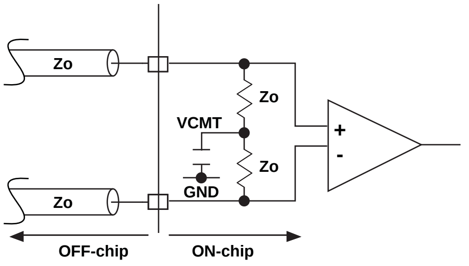
There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Differential Input Termination

The LatticeSC device allows two types of differential termination. The first is a single resistor across the differential inputs. The second is a center-tapped system where each input is terminated to the on-chip termination bus V_{CMT}. The V_{CMT} bus is DC-coupled through an internal capacitor to ground.

Figure 2-29 shows the differential termination schemes and Table 2-9 shows the nominal values of the termination resistors.

Figure 2-29. Differential Termination Scheme

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Differential termination		
Differential and common mode termination		

Calibration

There are two calibration sources that are associated with the termination scheme used in the LatticeSC devices:

- DIFFR – This pin occurs in each bank that supports differential drivers and must be connected through a 1K+/-1% resistor to ground if differential outputs are used. Note that differential drivers are not supported in banks 1, 4 and 5.
- XRES – There is one of these pins per device. It is used for several functions including calibrating on-chip termination. This pin should always be connected through a 1K+/-1% resistor to ground.

The LatticeSC devices support two modes of calibration:

- Continuous – In this mode the SC devices continually calibrate the termination resistances. Calibration happens several times a second. Using this mode ensures that termination resistances remain calibrated as the silicon junction temperature changes.
- User Request – In this mode the calibration circuit operates continuously. However, the termination resistor values are only updated on the assertion of the calibration_update signal available to the core logic.

For more information on calibration, refer to the details of additional technical documentation at the end of this data sheet.

Hot Socketing

The LatticeSC devices have been carefully designed to ensure predictable behavior during power-up and power-down. To ensure proper power sequencing, care must be taken during power-up and power-down as described below. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits,

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	$0 <= V_{IN} <= V_{IH}$ (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	$-3 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{CC} + 4 > V_{IN} \geq V_{CC} + 1$	$25 + (V_{IN} - V_{CC} -1)/0.015$	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

Initialization and Standby Supply Current

The table below indicates initialization and standby supply current while operating at 85°C junction temperature (T_J), which is the high end of the commercial temperature range, and 105°C, which is the high end of the industrial temperature range. This data assumes all outputs are tri-stated and all inputs are configured as LVCMOS and held at V_{CCIO} or GND. The remaining SERDES supply current for V_{DDIB} and V_{DDOB} is detailed in the SERDES section of this data sheet. For power at your design temperature, it is recommended to use the Power Calculator tool which is accessible in ispLEVER or can be used as a standalone tool. For more information on supply current, see the reference to additional technical documentation available at the end of this data sheet.

Over Recommended Operating Conditions

				25°C Typ.[1]	85°C Max.[2]		105°C Max.[2]	Units
Symbol	**Condition**	**Parameter**	**Device**	**All**	**-5, -6**	**-7**	**-5, -6**	
I_{CC}	(VCC = 1.2V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	65	449	678	755	mA
			LFSC/M25	113	798	1255	1343	mA
			LFSC/M40	159	1178	2006	1981	mA
			LFSC/M80	276	2122	3827	3569	mA
			LFSC/M115	454	3376	—	5679	mA
	(VCC = 1.0V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	45	312	471	524	mA
			LFSC/M25	79	554	872	933	mA
			LFSC/M40	110	818	1393	1375	mA
			LFSC/M80	191	1473	2658	2478	mA
			LFSC/M115	315	2344	—	3943	mA
I_{CC12}		1.2V Power Supply Current for Configuration Logic, FPGA PLL, SERDES PLL and SERDES Analog Supplies	LFSC/M15	23	39	59	35	mA
			LFSC/M25	25	50	78	56	mA
			LFSC/M40	31	78	133	89	mA
			LFSC/M80	50	108	195	123	mA
			LFSC/M115	65	131	—	154	mA
I_{CCAUX}		Auxiliary Operating Power Supply Current	LFSC/M15	7	12	19	14	mA
			LFSC/M25	9	16	25	18	mA
			LFSC/M40	12	23	39	25	mA
			LFSC/M80	13	25	45	23	mA
			LFSC/M115	16	27	—	26	mA
I_{CCIO} and I_{CCJ}		Bank Power Supply Current (per bank)	LFSC/M15	0.1	0.2	0.3	0.2	mA
			LFSC/M25	0.3	0.6	1.0	0.7	mA
			LFSC/M40	0.4	0.9	1.5	1.0	mA
			LFSC/M80	0.5	1.1	2.1	1.3	mA
			LFSC/M115	0.7	1.5	—	1.8	mA

1. I_{CC} is specified at T_J = 25°C and typical V_{CC}.
2. I_{CC} is specified at the respective commercial and industrial maximum T_J and V_{CC} limits.

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

LatticeSC/M Internal Timing Parameters[1]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
PFU Logic Mode Timing									
t_{LUT4_PFU}	CTOF_DEL	LUT4 delay (A to D inputs to F output)	—	0.045	—	0.050	—	0.054	ns
t_{LUT5_PFU}	MTOOFX_DEL	LUT5 delay (inputs to output)	—	0.152	—	0.172	—	0.192	ns
t_{LSR_PFU}	LSR_DEL	Set/Reset to output (asynchronous)	—	0.378	—	0.426	—	0.474	ns
t_{SUM_PFU}	M_SET	Clock to Mux (M0,M1) input setup time	0.113	—	0.131	—	0.148	—	ns
t_{HM_PFU}	M_HLD	Clock to Mux (M0,M1) input hold time	-0.041	—	-0.046	—	-0.052	—	ns
t_{SUD_PFU}	DIN_SET	Clock to D input setup time	0.072	—	0.083	—	0.094	—	ns
t_{HD_PFU}	DIN_HLD	Clock to D input hold time	-0.028	—	-0.032	—	-0.035	—	ns
t_{CK2Q_PFU}	REG_DEL	Clock to Q delay, D-type register configuration	—	0.224	—	0.252	—	0.279	ns
t_{LE2Q_PFU}	LTCH_DEL	Clock to Q delay latch configuration	—	0.294	—	0.331	—	0.367	ns
t_{LD2Q_PFU}	TLTCH_DEL	D to Q throughput delay when latch is enabled	—	0.300	—	0.338	—	0.376	ns
PFU Memory Mode Timing									
t_{CORAM_PFU}	CLKTOF_DEL	Clock to Output	—	0.575	—	0.649	—	0.724	ns
t_{SUDATA_PFU}	DIN_SET	Data Setup Time	-0.024	—	-0.026	—	-0.027	—	ns
t_{HDATA_PFU}	DIN_HLD	Data Hold Time	0.075	—	0.084	—	0.094	—	ns
t_{SUADDR_PFU}	WAD_SET	Address Setup Time	-0.176	—	-0.196	—	-0.215	—	ns
t_{HADDR_PFU}	WAD_HLD	Address Hold Time	0.110	—	0.124	—	0.138	—	ns
t_{SUWREN_PFU}	WE_SET	Write/Read Enable Setup Time	0.014	—	0.019	—	0.024	—	ns
t_{HWREN_PFU}	WE_HLD	Write/Read Enable Hold Time	0.078	—	0.086	—	0.094	—	ns
PIC Timing									
PIO Input/Output Buffer Timing									
t_{IN_PIO}	IN_DEL	Input Buffer Delay(LVCMOS25)	—	0.578	—	0.661	—	0.744	ns
t_{OUT_PIO}	DOPADI_DEL	Output Buffer Delay(LVCMOS25)	—	2.712	—	3.027	—	3.395	ns
t_{SUI_PIO}	DIN_SET	Input Register Setup Time (Data Before Clock)	0.277	—	0.312	—	0.348	—	ns
t_{HI_PIO}	DIN_HLD	Input Register Hold Time (Data after Clock)	-0.267	—	-0.306	—	-0.345	—	ns
t_{COO_PIO}	CK_DEL	Output Register Clock to Output Delay	—	0.513	—	0.571	—	0.639	ns
t_{SUCE_PIO}	CE_SET	Input Register Clock Enable Setup Time	—	0.000	—	0.000	—	0.000	ns
t_{HCE_PIO}	CE_HLD	Input Register Clock Enable Hold Time	—	0.129	—	0.145	—	0.161	ns
t_{SULSR_PIO}	LSR_SET	Set/Reset Setup Time	0.057	—	0.060	—	0.063	—	ns
t_{HLSR_PIO}	LSR_HLD	Set/Reset Hold Time	-0.151	—	-0.159	—	-0.169	—	ns
t_{LE2Q_PIO}	CK_DEL	Input Register Clock to Q delay latch configuration	—	0.335	—	0.372	—	0.410	ns
t_{LD2Q_PIO}	DIN_DEL	Input Register D to Q throughput delay when latch is enabled	—	0.578	—	0.647	—	0.717	ns

Figure 3-12. Waveforms First Read after Full Flag

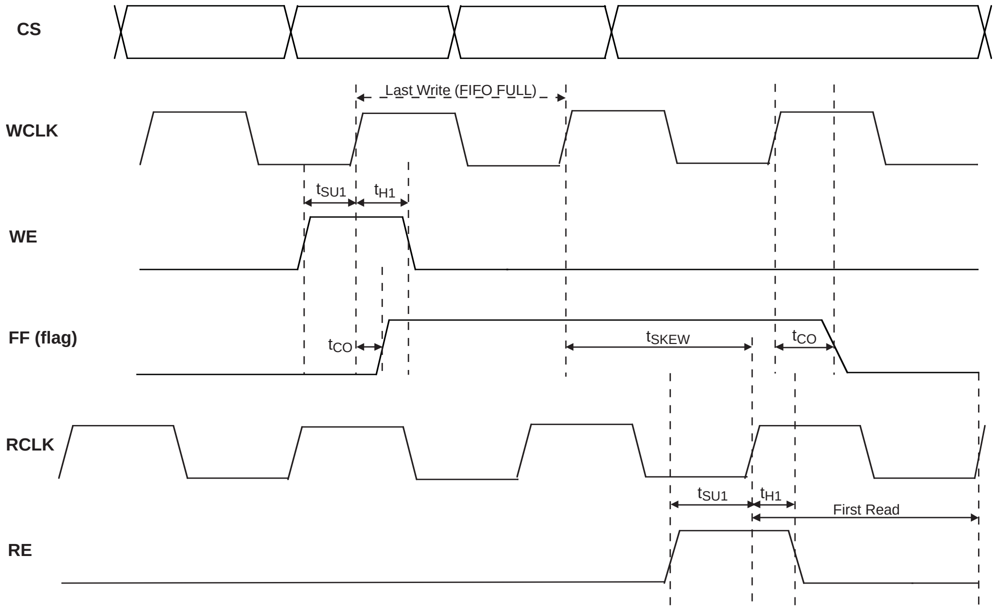
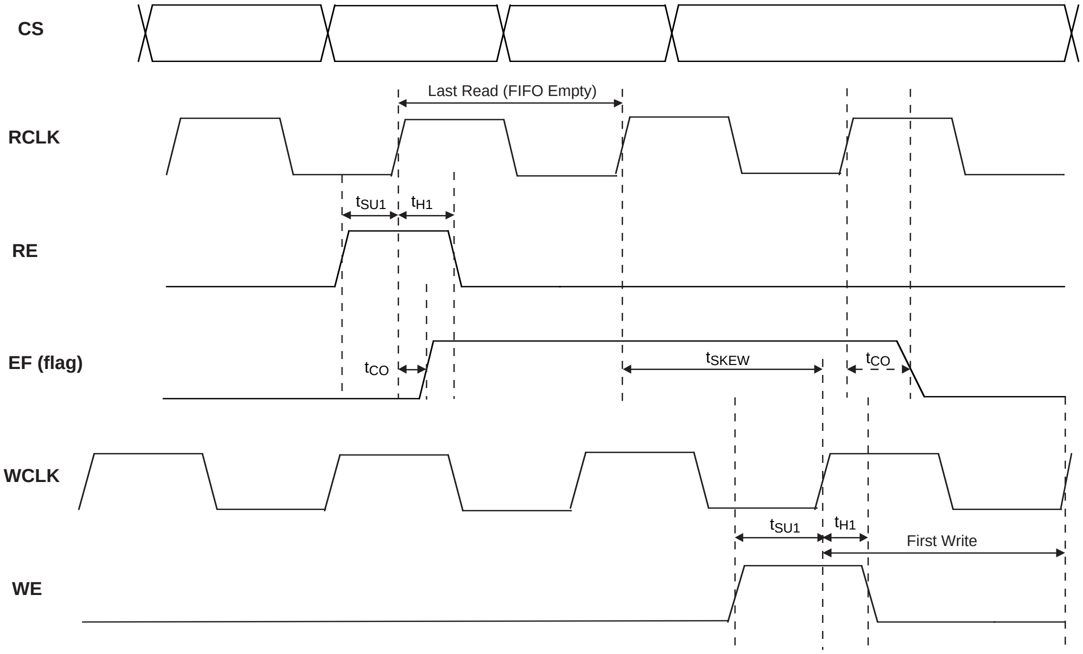


Figure 3-13. Waveform First Write after Empty Flag



Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESP_[ULC/URC]	—	Calibration resistor to be placed between this pin and either ground or RESPN_[ULC/URC]. RESPN_[ULC/URC] is available on select packages. If available, connection of calibration resistor between RESP_[ULC/URC] and RESPN_[ULC/URC] takes precedence over connection of calibration resistor between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
RESPN_[ULC/URC]	—	Available on selected packages. If available, calibration resistor should be placed between RESP_[ULC/URC] and RESPN_[ULC/URC] instead of between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
[A:D]_VDDIBx_[L/R]	—	Input buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDOBx_[L/R]	—	Output buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDAX25_[L/R]	—	Auxiliary power for input and output termination (2.5V) on left [L] or right [R] side of device.

1. The ispLEVER software tools may specify VDDRX, VDDTX, VDDP and VCCL pins. These pins should be considered VCC12 pins.

Note: Signals listed as Signal A / Signal B define the same physical pin that is used for different functions based on configuration mode.

Pin Information Summary

Pin Type		256 fpBGA	900 fpBGA		1020 fcBGA	
		LFSC/M15	LFSC/M15	LFSC/M25	LFSC/M25	LFSC/M40
Single Ended User I/O		139	300	378	476	562
Differential Pair User I/O		60	141	182	235	277
LVDS Output Pairs		22	44	60	60	78
Configuration	Dedicated	9	11	11	11	11
	Muxes/MPI sysBus	0	55	55	55	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		2	4	4	4	4
VCC		10	46	46	40	40
VCC12		10	35	35	36	36
VCCAUX		10	36	36	32	32
VCCIO	Bank 1	3	18	18	10	10
	Bank 2	2	14	14	8	8
	Bank 3	2	15	15	10	10
	Bank 4	3	15	15	10	10
	Bank 5	3	15	15	10	10
	Bank 6	2	15	15	10	10
	Bank 7	2	16	16	8	8
VTT	Bank 2	0	2	2	2	2
	Bank 3	0	3	3	3	3
	Bank 4	0	3	3	3	3
	Bank 5	0	3	3	3	3
	Bank 6	0	3	3	3	3
	Bank 7	0	2	2	2	2
GND		26	177	177	134	134
NC		0	102	24	92	6
Single Ended User / Differential I/O per Bank	Bank 1	21/8	63/30	63/30	68/32	68/32
	Bank 2	15/7	26/13	30/15	34/17	54/27
	Bank 3	19/8	43/20	62/29	84/42	94/47
	Bank 4	25/11	50/22	66/32	84/41	99/48
	Bank 5	25/11	49/23	65/32	88/44	99/49
	Bank 6	19/8	43/20	62/29	84/42	94/47
	Bank 7	15/7	26/13	30/15	34/17	54/27
LVDS Output Pairs Per Bank	Bank 2	5	7	9	9	15
	Bank 3	6	15	21	21	24
	Bank 6	6	15	21	21	24
	Bank 7	5	7	9	9	15
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		28	60	60	108	108
Total		256	900	900	1020	1152

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

	LFSC/M15		
Ball Number	**Ball Function**	**VCCIO Bank**	**Dual Function**
C5	A_VDDIB1_L	-	
A5	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N
A4	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B4	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C4	A_VDDOB1_L	-	
B3	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C3	A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
B2	A_HDINN0_L	-	PCS 360 CH 0 IN N
A2	A_HDINP0_L	-	PCS 360 CH 0 IN P
C2	A_VDDIB0_L	-	
A1	GND	-	
A16	GND	-	
B10	GND	-	
C13	GND	-	
D15	GND	-	
D3	GND	-	
E11	GND	-	
F13	GND	-	
G14	GND	-	
G2	GND	-	
G8	GND	-	
H10	GND	-	
J7	GND	-	
K15	GND	-	
K3	GND	-	
K9	GND	-	
M6	GND	-	
N11	GND	-	
N14	GND	-	
N2	GND	-	
P10	GND	-	
P4	GND	-	
R13	GND	-	
R7	GND	-	
G10	VCC	-	
G7	VCC	-	
G9	VCC	-	
H7	VCC	-	
H8	VCC	-	
H9	VCC	-	
J10	VCC	-	
J8	VCC	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D14	PT15B	1	A15/MPI_ADDR29	PT25B	1	A15/MPI_ADDR29
D13	PT15A	1	A17/MPI_ADDR31	PT25A	1	A17/MPI_ADDR31
F12	PT13D	1	A19/MPI_TSIZ1	PT24D	1	A19/MPI_TSIZ1
F13	PT13C	1	A20/MPI_BDIP	PT24C	1	A20/MPI_BDIP
B12	PT11B	1	A18/MPI_TSIZ0	PT24B	1	A18/MPI_TSIZ0
B11	PT11A	1	MPI_TEA	PT24A	1	MPI_TEA
E12	PT10D	1	D14/MPI_DATA14	PT23D	1	D14/MPI_DATA14
D12	PT10C	1	DP1/MPI_PAR1	PT23C	1	DP1/MPI_PAR1
G10	PT9B	1	A21/MPI_BURST	PT23B	1	A21/MPI_BURST
G9	PT9A	1	D15/MPI_DATA15	PT23A	1	D15/MPI_DATA15
C10	A_VDDIB3_L	-		A_VDDIB3_L	-	
E9	VCC12	-		VCC12	-	
B10	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A10	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
D9	VCC12	-		VCC12	-	
A9	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C9	A_VDDOB3_L	-		A_VDDOB3_L	-	
A8	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C8	A_VDDOB2_L	-		A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E8	VCC12	-		VCC12	-	
B8	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
B7	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
C7	A_VDDIB2_L	-		A_VDDIB2_L	-	
D8	VCC12	-		VCC12	-	
C6	A_VDDIB1_L	-		A_VDDIB1_L	-	
E7	VCC12	-		VCC12	-	
B6	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A6	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
D7	VCC12	-		VCC12	-	
A5	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C5	A_VDDOB1_L	-		A_VDDOB1_L	-	
A4	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C4	A_VDDOB0_L	-		A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E6	VCC12	-		VCC12	-	
B4	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
B3	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
C3	A_VDDIB0_L	-		A_VDDIB0_L	-	
D6	VCC12	-		VCC12	-	
L5	NC	-		PL21A	7	
M5	NC	-		PL21B	7	
G2	NC	-		PL20A	7	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).
2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
G27	A_REFCLKP_L	-	
H27	A_REFCLKN_L	-	
H25	VCC12	-	
H26	RESP_ULC	-	
B33	RESETN	1	
C34	TSALLN	1	
D34	DONE	1	
C33	INITN	1	
J27	M0	1	
K27	M1	1	
M26	M2	1	
L26	M3	1	
F30	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
G30	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
H28	PL15C	7	
J28	PL15D	7	
F31	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G31	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N25	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P25	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
D33	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
E33	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
H29	PL18C	7	
J29	PL18D	7	VREF2_7
F32	PL19A	7	
G32	PL19B	7	
P26	PL19C	7	
N26	PL19D	7	
H30	PL26A	7	
J30	PL26B	7	
L28	PL26C	7	
M28	PL26D	7	
J31	PL43A	7	
K31	PL43B	7	
L27	PL43C	7	VREF1_7
M27	PL43D	7	DIFFR_7
J32	PL45A	7	
K32	PL45B	7	
L29	PL45C	7	
M29	PL45D	7	
H33	PL47A	7	
J33	PL47B	7	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
L21	PT55D	1	A16/MPI_ADDR30
L20	PT55C	1	D13/MPI_DATA13
D20	PT55B	1	A15/MPI_ADDR29
E20	PT55A	1	A17/MPI_ADDR31
L19	PT54D	1	A19/MPI_TSIZ1
K19	PT54C	1	A20/MPI_BDIP
D21	PT54B	1	A18/MPI_TSIZ0
E21	PT54A	1	MPI_TEA
M20	PT51D	1	D14/MPI_DATA14
M19	PT51C	1	DP1/MPI_PAR1
F21	PT51B	1	A21/MPI_BURST
G21	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-	
J24	B_REFCLKN_L	-	
L22	VCC12	-	
E26	B_VDDIB3_L	-	
G22	VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-	
G23	VCC12	-	
D27	B_VDDIB1_L	-	
G24	VCC12	-	
E24	B_HDINP1_L	-	PCS 361 CH 1 IN P
F24	B_HDINN1_L	-	PCS 361 CH 1 IN N
A23	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
L25	VCC12	-	
B23	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
D24	B_VDDOB1_L	-	
B24	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
D25	B_VDDOB0_L	-	
A24	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
K25	VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

	LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function
F25	B_HDINN0_L	-	PCS 361 CH 0 IN N
E25	B_HDINP0_L	-	PCS 361 CH 0 IN P
D28	B_VDDIB0_L	-	
G25	VCC12	-	
D29	A_VDDIB3_L	-	
C25	VCC12	-	
A25	A_HDINP3_L	-	PCS 360 CH 3 IN P
B25	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
E27	VCC12	-	
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
F26	A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
F27	A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E28	VCC12	-	
B28	A_HDINN2_L	-	PCS 360 CH 2 IN N
A28	A_HDINP2_L	-	PCS 360 CH 2 IN P
D30	A_VDDIB2_L	-	
C28	VCC12	-	
D31	A_VDDIB1_L	-	
C29	VCC12	-	
A29	A_HDINP1_L	-	PCS 360 CH 1 IN P
B29	A_HDINN1_L	-	PCS 360 CH 1 IN N
A30	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
E29	VCC12	-	
B30	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
F28	A_VDDOB1_L	-	
B31	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
F29	A_VDDOB0_L	-	
A31	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E30	VCC12	-	
B32	A_HDINN0_L	-	PCS 360 CH 0 IN N
A32	A_HDINP0_L	-	PCS 360 CH 0 IN P
D32	A_VDDIB0_L	-	
C32	VCC12	-	
E34	PL30A	7	
F34	PL30B	7	
F33	PL34A	7	
G33	PL34B	7	
K30	PL38A	7	
L30	PL38B	7	
G34	PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F5	VCC12	-		VCC12	-	
B14	C_HDOUTP3_R	-	PCS 3E2 CH 3 OUT P	C_HDOUTP3_R	-	PCS 3E2 CH 3 OUT P
E13	C_HDINN3_R	-	PCS 3E2 CH 3 IN N	C_HDINN3_R	-	PCS 3E2 CH 3 IN N
D13	C_HDINP3_R	-	PCS 3E2 CH 3 IN P	C_HDINP3_R	-	PCS 3E2 CH 3 IN P
F12	VCC12	-		VCC12	-	
G14	C_VDDIB3_R	-		C_VDDIB3_R	-	
F11	VCC12	-		VCC12	-	
K15	C_REFCLKN_R	-		C_REFCLKN_R	-	
J15	C_REFCLKP_R	-		C_REFCLKP_R	-	
G15	VCC12	-		VCC12	-	
H16	D_VDDIB0_R	-		D_VDDIB0_R	-	
D14	D_HDINP0_R	-	PCS 3E3 CH 0 IN P	D_HDINP0_R	-	PCS 3E3 CH 0 IN P
E14	D_HDINN0_R	-	PCS 3E3 CH 0 IN N	D_HDINN0_R	-	PCS 3E3 CH 0 IN N
F6	VCC12	-		VCC12	-	
B15	D_HDOUTP0_R	-	PCS 3E3 CH 0 OUT P	D_HDOUTP0_R	-	PCS 3E3 CH 0 OUT P
M13	D_VDDOB0_R	-		D_VDDOB0_R	-	
A15	D_HDOUTN0_R	-	PCS 3E3 CH 0 OUT N	D_HDOUTN0_R	-	PCS 3E3 CH 0 OUT N
F8	D_VDDOB1_R	-		D_VDDOB1_R	-	
A16	D_HDOUTN1_R	-	PCS 3E3 CH 1 OUT N	D_HDOUTN1_R	-	PCS 3E3 CH 1 OUT N
F7	VCC12	-		VCC12	-	
B16	D_HDOUTP1_R	-	PCS 3E3 CH 1 OUT P	D_HDOUTP1_R	-	PCS 3E3 CH 1 OUT P
F15	D_HDINN1_R	-	PCS 3E3 CH 1 IN N	D_HDINN1_R	-	PCS 3E3 CH 1 IN N
E15	D_HDINP1_R	-	PCS 3E3 CH 1 IN P	D_HDINP1_R	-	PCS 3E3 CH 1 IN P
K17	VCC12	-		VCC12	-	
F13	D_VDDIB1_R	-		D_VDDIB1_R	-	
C14	VCC12	-		VCC12	-	
C15	D_VDDIB2_R	-		D_VDDIB2_R	-	
D16	D_HDINP2_R	-	PCS 3E3 CH 2 IN P	D_HDINP2_R	-	PCS 3E3 CH 2 IN P
E16	D_HDINN2_R	-	PCS 3E3 CH 2 IN N	D_HDINN2_R	-	PCS 3E3 CH 2 IN N
C11	VCC12	-		VCC12	-	
B17	D_HDOUTP2_R	-	PCS 3E3 CH 2 OUT P	D_HDOUTP2_R	-	PCS 3E3 CH 2 OUT P
C9	D_VDDOB2_R	-		D_VDDOB2_R	-	
A17	D_HDOUTN2_R	-	PCS 3E3 CH 2 OUT N	D_HDOUTN2_R	-	PCS 3E3 CH 2 OUT N
D17	D_VDDOB3_R	-		D_VDDOB3_R	-	
A18	D_HDOUTN3_R	-	PCS 3E3 CH 3 OUT N	D_HDOUTN3_R	-	PCS 3E3 CH 3 OUT N
C17	VCC12	-		VCC12	-	
B18	D_HDOUTP3_R	-	PCS 3E3 CH 3 OUT P	D_HDOUTP3_R	-	PCS 3E3 CH 3 OUT P
F17	D_HDINN3_R	-	PCS 3E3 CH 3 IN N	D_HDINN3_R	-	PCS 3E3 CH 3 IN N
E17	D_HDINP3_R	-	PCS 3E3 CH 3 IN P	D_HDINP3_R	-	PCS 3E3 CH 3 IN P
F14	VCC12	-		VCC12	-	
F16	D_VDDIB3_R	-		D_VDDIB3_R	-	
G16	VCC12	-		VCC12	-	
M17	D_REFCLKN_R	-		D_REFCLKN_R	-	
L17	D_REFCLKP_R	-		D_REFCLKP_R	-	
G18	PT77D	1	HDC/SI	PT93D	1	HDC/SI

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B22	PT61B	1	A3/MPI_ADDR17	PT69B	1	A3/MPI_ADDR17
B23	PT61A	1	A4/MPI_ADDR18	PT69A	1	A4/MPI_ADDR18
K23	PT60D	1	D25/PCLKC1_5/MPI_DATA25	PT66D	1	D25/PCLKC1_5/MPI_DATA25
J23	PT60C	1	D26/PCLKT1_5/MPI_DATA26	PT66C	1	D26/PCLKT1_5/MPI_DATA26
D22	PT60B	1	A5/MPI_ADDR19	PT66B	1	A5/MPI_ADDR19
E22	PT60A	1	A6/MPI_ADDR20	PT66A	1	A6/MPI_ADDR20
K22	PT59D	1	D27/MPI_DATA27	PT63D	1	D27/MPI_DATA27
J22	PT59C	1	VREF1_1	PT63C	1	VREF1_1
D23	PT59B	1	A7/MPI_ADDR21	PT63B	1	A7/MPI_ADDR21
C23	PT59A	1	A8/MPI_ADDR22	PT63A	1	A8/MPI_ADDR22
L23	PT57D	1	D28/PCLKC1_6/MPI_DATA28	PT61D	1	D28/PCLKC1_6/MPI_DATA28
M23	PT57C	1	D29/PCLKT1_6/MPI_DATA29	PT61C	1	D29/PCLKT1_6/MPI_DATA29
A24	PT57B	1	A9/MPI_ADDR23	PT61B	1	A9/MPI_ADDR23
B24	PT57A	1	A10/MPI_ADDR24	PT61A	1	A10/MPI_ADDR24
K25	PT56D	1	D30/PCLKC1_7/MPI_DATA30	PT58D	1	D30/PCLKC1_7/MPI_DATA30
J25	PT56C	1	D31/PCLKT1_7/MPI_DATA31	PT58C	1	D31/PCLKT1_7/MPI_DATA31
F23	PT56B	1	A11/MPI_ADDR25	PT58B	1	A11/MPI_ADDR25
F22	PT56A	1	A12/MPI_ADDR26	PT58A	1	A12/MPI_ADDR26
J26	PT55D	1	D11/MPI_DATA11	PT57D	1	D11/MPI_DATA11
K26	PT55C	1	D12/MPI_DATA12	PT57C	1	D12/MPI_DATA12
E23	PT55B	1	A13/MPI_ADDR27	PT57B	1	A13/MPI_ADDR27
E24	PT55A	1	A14/MPI_ADDR28	PT57A	1	A14/MPI_ADDR28
G23	PT53D	1	A16/MPI_ADDR30	PT55D	1	A16/MPI_ADDR30
G24	PT53C	1	D13/MPI_DATA13	PT55C	1	D13/MPI_DATA13
F26	PT53B	1	A15/MPI_ADDR29	PT55B	1	A15/MPI_ADDR29
F27	PT53A	1	A17/MPI_ADDR31	PT55A	1	A17/MPI_ADDR31
H25	PT52D	1	A19/MPI_TSIZ1	PT54D	1	A19/MPI_TSIZ1
H24	PT52C	1	A20/MPI_BDIP	PT54C	1	A20/MPI_BDIP
C25	PT52B	1	A18/MPI_TSIZ0	PT54B	1	A18/MPI_TSIZ0
C26	PT52A	1	MPI_TEA	PT54A	1	MPI_TEA
K24	PT51D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
J24	PT51C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F24	PT51B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
F25	PT51A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
L26	D_REFCLKP_L	-		D_REFCLKP_L	-	
M26	D_REFCLKN_L	-		D_REFCLKN_L	-	
G27	VCC12	-		VCC12	-	
C29	D_VDDIB3_L	-		D_VDDIB3_L	-	
F28	VCC12	-		VCC12	-	
D26	D_HDINP3_L	-	PCS 363 CH 3 IN P	D_HDINP3_L	-	PCS 363 CH 3 IN P
E26	D_HDINN3_L	-	PCS 363 CH 3 IN N	D_HDINN3_L	-	PCS 363 CH 3 IN N
B25	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P
D24	VCC12	-		VCC12	-	
A25	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N
E25	D_VDDOB3_L	-		D_VDDOB3_L	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FF1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FF1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FF1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FC1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FC1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FC1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FF1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FF1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FF1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FC1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FC1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FC1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.